COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: D01

PCB VIEWED FROM TOP SIDE  BOARD #: TIDA-01373  REV: E1  SUN REV: Not In VersionControl
TID #: TIDA-01373
PLOT NAME = Top Assembly Drawing  GENERATED : 2/3/2017  1:14:11 PM  TEXAS INSTRUMENTS
COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: DOI

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